

PCN Number:	20160808000	PCN Date:	8/19/2016
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Title: Datasheet for TMDS181

Customer Contact:	PCN Manager	Dept:	Quality Services
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Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



TMDS181, TMDS181I

SLASE75B|–AUGUST 2015–REVISED APRIL 2016

Changes from Revision A (October 2015) to Revision B	Page
• Added V _{IL} "Low-level input voltage at HPD, OE" to the <i>Recommended Operating Conditions</i>	7
• Moved pin OE From: V _{IH} MIN value of 2 V To: V _{IH} MIN value of 2.6 V in the <i>Recommended Operating Conditions</i>	7
• Deleted the VDD_ramp and VCC_ramp MIN values in <i>Power-Up and Operation Timing Requirements</i>	12
• Changed Figure 1	12
• Changed text "address 22h (see Figure 31) through the I2C interface." To: "address 0Bh through the I2C interface." in <i>DDC Functional Description</i>	32
• Added Note to 11–400-kbps in Table 6	35
• Added Note to 11–400-kbps in Table 6	36



TMDS181, TMDS181I

SLASE75C –AUGUST 2015–REVISED JULY 2016

Changes from Revision B (April 2016) to Revision C	Page
• <i>Recommended Operating Conditions</i> , Changed the CONTROL PINS section	7
• <i>DDC, I²C, HPD, and ARC Electrical Characteristics</i> , Changed the DDC AND I ² C section	11

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMDS181	SLASE75A	SLASE75C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TMDS181>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
TMDS181IRGZR	TMDS181IRGZT	TMDS181RGZR	TMDS181RGZT

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com